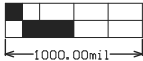
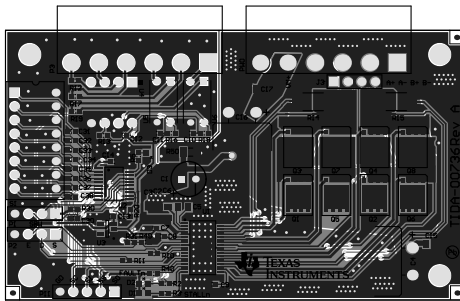


Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Top Layer	Copper	1.40mil		
4	Dielectric1	FR-4	59.20mil	4.8	
5	Bottom Layer	Copper	1.40mil		
6	Bottom Solder	Solder Resist	0.40mil	3.5	
7	Bottom Overlay				

Z22 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.
 Z23 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
 Z24 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: [No Variations]

DESIGN INFORMATION	
MIN. TRACK WIDTH:	8_ML
MIN. CLEARANCE:	0.2 mm
MIN. VIA PAD SIZE:	24_ML
MINIMUM ANNULAR RING 0.05mm (2ML) EXTERNAL PER IPC-D-275 CLASS 2 LEVEL C REGISTRATION TOLERANCES: METAL +/- 5_ML HOLES +/- 3_ML HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3_ML	
MATERIAL:	
<input type="checkbox"/> FR-408	<input checked="" type="checkbox"/> FR-4 High Tg <input type="checkbox"/> OTHER _____
THICKNESS:	<input checked="" type="checkbox"/> 62 MIL (1.6mm) +/-10% <input type="checkbox"/> OTHER _____
TOLERANCE:	<input checked="" type="checkbox"/> ANSI IPC-6012 TYPE 3 CLASS 2 <input type="checkbox"/> OTHER +/- _____
BOW & TWIST:	<input checked="" type="checkbox"/> ANSI IPC-6012 TYPE 3 CLASS 2 <input type="checkbox"/> OTHER +/- _____
DRILLING:	
REFERENCE:	<input checked="" type="checkbox"/> AS SHOWN <input checked="" type="checkbox"/> NC_DRILL FILES
PTH MIN COPPER THICKNESS:	<input checked="" type="checkbox"/> 1MIL <input type="checkbox"/> OTHER _____
BOARD FINISH:	
SILKSCREEN:	<input checked="" type="checkbox"/> TOP <input checked="" type="checkbox"/> BOTTOM
SILKSCREEN COLOR:	<input checked="" type="checkbox"/> WHITE <input type="checkbox"/> OTHER _____
SOLDER RESIST COLOR:	<input checked="" type="checkbox"/> GREEN <input type="checkbox"/> OTHER _____ <input checked="" type="checkbox"/> MATTE <input type="checkbox"/> SEMI-GLOSS
SURFACE FINISH:	<input checked="" type="checkbox"/> IMMERSION GOLD (ENIG) <input type="checkbox"/> ENEPIG <input type="checkbox"/> IMM. TIN/SILVER OR EQUIV <input type="checkbox"/> OTHER _____
ARRAY/PANEL:	<input type="checkbox"/> CUT AND TRM PER M1 BOARD OUTLINE <input type="checkbox"/> N.C. ROUTE <input checked="" type="checkbox"/> V. SCORE
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:	
<input checked="" type="checkbox"/> ANSI IPC-A-600F CLASS ->	<input type="checkbox"/> 1 <input checked="" type="checkbox"/> 2 <input type="checkbox"/> 3
<input checked="" type="checkbox"/> UL 94V-0 <input checked="" type="checkbox"/> RoHS	<input type="checkbox"/> OTHER PER ORDER
ADDITIONAL REQUIREMENTS:	
MICROSECTION:	<input type="checkbox"/> YES
BARE BOARD ELEC. TEST:	<input type="checkbox"/> NONE <input checked="" type="checkbox"/> REQUIRED <input type="checkbox"/> PER ORDER
MANUFACTURER'S UL:	<input type="checkbox"/> RAL <input type="checkbox"/> METAL <input checked="" type="checkbox"/> SILK



PROJECT TITLE:
 Universal Stepper Motor Driver
 DESIGNED FOR:
 Public Release
 FILE NAME:
 TIDA-00736_PCB.PcbDoc

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-00736	REV: Rev A	SUN REV: Not In VersionControl
M9 Title Sheet	TID #: 00736		
PLOT NAME = Multilayer Composite Print	GENERATED : 12/14/2015 11:54:53 AM		TEXAS INSTRUMENTS

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ENGINEER: Wilson Zuo	LAYOUT BY: Wilson Zuo
SCALE: 1.00	ALTUM DESIGNER VERSION: 14.3.19.51423

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